

# Micron 9400 SSD Series Technical Product Specification

For additional technical and warranty information, contact your Micron sales representative.

## Features

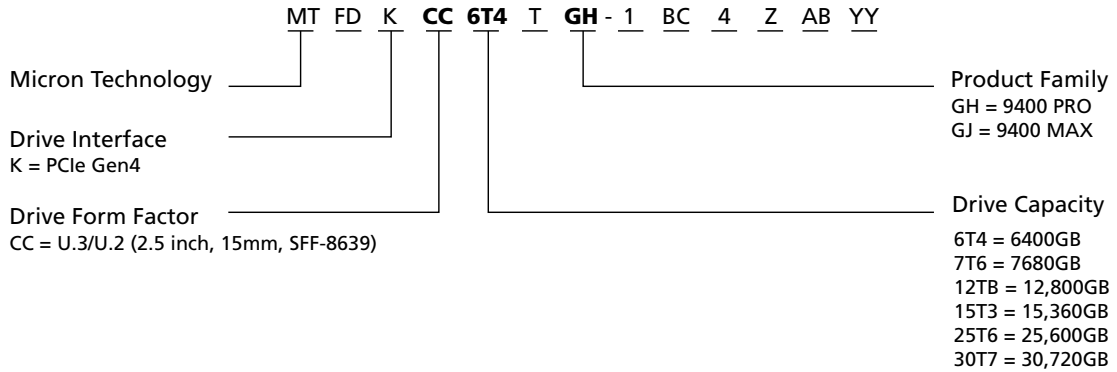
- Micron®3D TLC NANDFlash
- PCI Express Gen4
  - U.3/U.2 single port (x4)
- NVMe Express 1.4
  - Number of name spaces supported: 128
  - Weighted round robin with urgent arbitration supported
- Capacity (unformatted)
  - PRO: 3840GB, 7680GB, 15,360GB, 30,720GB
  - MAX: 3200GB, 6400GB, 12,800GB, 25,600GB
- Endurance: Total bytes written (TBW)
  - 3,200GB: 17,520TB
  - 3,840GB: 7,008TB
  - 6,400GB: 35,040TB
  - 7,680GB: 14,016TB
  - 12,800GB: 70,080TB
  - 15,360GB: 28,032TB
  - 25,600GB: 140,160TB
  - 30,720GB: 56,064TB
- Enterprise sector size support = 512 and 4096-byte sector size (configurable)
- Security: Digitally signed firmware
- Surprise insertion/surprise removal (SISR) and hot-plug capable
- Self-monitoring, analysis, and reporting technology (SMART)
- Performance<sup>1</sup>
  - Sequential 128KB READ: Up to 6800 MB/s
  - Sequential 128KB WRITE: Up to 6800 MB/s
  - Random 4KB READ: Up to 1,500,000 IOPS
  - Random 4KB WRITE: Up to 800,000 IOPS
- Latency<sup>2,3</sup>
  - READ (TYP): 71µs
  - WRITE (TYP): 15µs
- Reliability
  - MTTF: 2 million device hours<sup>4</sup>
  - Static and dynamic wear leveling
  - Uncorrectable bit error rate (UBER): <1 sector per 10<sup>17</sup> bits read
  - End-to-end data protection
  - Full power-loss protection
- Operating temperature<sup>5</sup>
  - Commercial (0°C to +70°C)
- Field upgradeable firmware
- Form factor
  - U.3/U.2: 100.45 x 70.10 x 15.00mm
- Electrical specification
  - Power supply: 12V ±8%
  - AUX supply: 3.3V ±5%

- Notes: 1. Steady state as defined by SNIA Solid State Storage Performance Test Specification Enterprise v1.1.
2. 4KB, queue depth 1 transfers used for READ/WRITE latency values.
3. TYP: Median, 50th percentile
4. Product achieves MTTF based on population statistics not relevant to individual units.
5. Temperature measured by SMART.

### Part Numbering Information

Micron 9400 SSDs are available in different configurations and capacities. The chart below is a comprehensive list of options; not all options listed can be combined to define an offered product. Visit [www.micron.com](http://www.micron.com) for a list of valid part numbers.

**Figure 1: Part Number Chart**



## Important Notes and Warnings

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## Performance

Measured performance can vary for a number of reasons. The major factors affecting drive performance are the capacity of the drive and the interface of the host. Additionally, overall system performance can affect the measured drive performance. When comparing drives, it is recommended that all system variables are the same, and only the drive being tested varies.

Performance numbers will vary depending on the host system configuration.

**Table 1: Drive Performance – PRO**

Parameter: Power State 0	7,680GB	15,360GB	30,720GB	Unit
Sequential READ (128KB transfer)	7000	7000	7000	MB/s
Sequential WRITE (128KB transfer)	7000	7000	7000	MB/s
Random READ (4KB transfer)	1600	1600	1500	KIOPS
Random WRITE (4KB transfer)	300	300	300	KIOPS
70/30 Random READ/WRITE (4KB transfer)	770	780	770	KIOPS
READ Latency (TYP)	69	69	69	us
WRITE Latency (TYP)	10	10	10	us
READ Latency (99%)	85	85	85	us
WRITE Latency (99%)	30	30	30	us

**Table 2: Drive Performance – MAX**

Parameter: Power State 0	6,400GB	12,800GB	25,600GB	Unit
Sequential READ (128KB transfer)	7000	7000	7000	MB/s
Sequential WRITE (128KB transfer)	7000	7000	7000	MB/s
Random READ (4KB transfer)	1600	1600	1500	KIOPS
Random WRITE (4KB transfer)	600	600	550	KIOPS
70/30 Random READ/WRITE (4KB transfer)	930	940	900	KIOPS
READ Latency (TYP)	69	69	69	us
WRITE Latency (TYP)	10	10	10	us
READ Latency (99%)	85	85	85	us
WRITE Latency(99%)	30	30	30	us

Notes: 1. Performance values measured under the following conditions:

- Steady state as defined by SNIA Solid State Storage Performance Test Specification Enterprise v1.1
- Drive write cache enabled
- NVMe power state 0
- Sequential workloads measured using FIO with a queue depth of 32
- Random READ workloads measured using FIO with a queue depth of 256
- Random WRITE workloads measured using FIO with a queue depth of 128

2. Performance values measured with the following system configuration:

- Generic X570 Motherboard
- AMD Ryzen 7 3700X 8-Core CPU @ 2.6 GHz
- DDR4 16GB @ 3200 MHz

3. Latency values measured under the following configuration:

- Random workloads using FIO with 4KB transfers and a queue depth of 1
- TYP = median, 50th percentile

4. System variations will affect measured results.



## Endurance

While actual endurance varies depending on conditions, the drive lifetime can be estimated based on capacity, assumed fixed-use models, ECC, and formatted sector size.

Lifetime estimates for the device are shown in the following tables in total bytes written.

**Table 3: Total Bytes Written**

Model	Capacity (GB)	4K Random Total Bytes Written (TB)	128K Sequential Total Bytes Written (TB)
PRO	7680	14,016	58,300
	15360	28,032	104,500
	30720	56,064	201,200
MAX	6400	35,040	74,200
	12800	70,080	143,100
	25600	140,160	282,600

Notes: 1. Values represent the theoretical maximum endurance for the given transfer size and type. Actual lifetime will vary by workload. Refer to Percentage Used in the SMART/Health Information (Log Identifier 02h) to check the device life used.

2. Total bytes written assuming drive is 100% full (user capacity) with workload of 100% random aligned 4KB and 100% sequential 128K Writes.

## Electrical Characteristics

**Table 4: Power Consumption – PRO**

Parameter: Power State 0	7,680GB	15,360GB	30,720GB	Unit
Active READ (maximum RMS)	17	18	21	W
Active Write (maximum RMS)	22	25	25	W
128K Sequential READ (average RMS)	11	13	14	W
128K Sequential WRITE (average RMS)	15	20	17	W
4K Random READ (average RMS)	13	15	16	W
4KB Random WRITE (average RMS)	17	19	18	W
4KB 70/30 Random READ/WRITE (average RMS)	17	18	18	W
Idle (average RMS)	5	5	5	W

**Table 5: Power Consumption – MAX**

Parameter: Power State 0	6,400GB	12,800GB	25,600GB	Unit
Active READ (maximum RMS)	16	18	21	W
Active Write (maximum RMS)	22	25	25	W
128K Sequential READ (average RMS)	11	16	14	W
128K Sequential WRITE (average RMS)	15	13	17	W
4K Random READ (average RMS)	13	15	16	W
4KB Random WRITE (average RMS)	16	17	18	W
4KB 70/30 Random READ/WRITE (average RMS)	14	15	17	W
Idle (average RMS)	5	5	5	W



**Table 6: Operating Voltage – U.3/U.2**

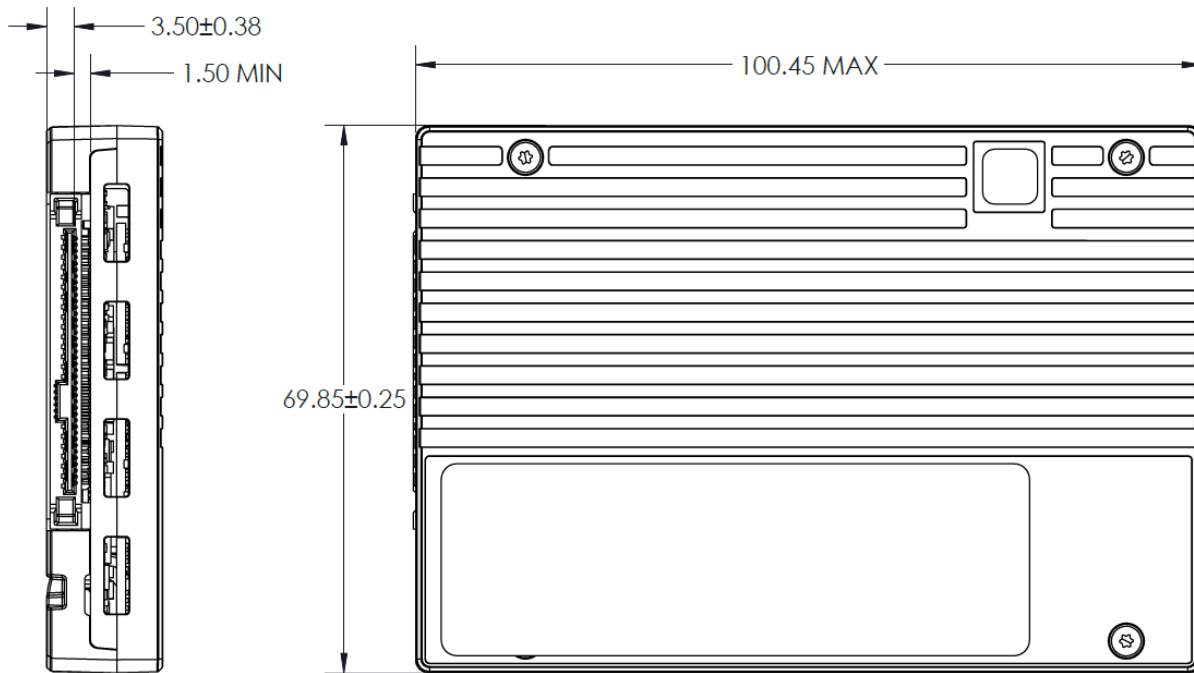
Power Rail	Electrical Parameter	Value
12V	Operating voltage	12 Vdc ( $\pm 8\%$ )
	MIN/MAX rise time	0.1ms/100ms
	Fall time	<5s
	MIN power-off time	50ms
	Inrush current (typical peak)	2.0A
3.3V <sub>AUX</sub>	Operating voltage	3.3 Vdc ( $\pm 5\%$ )
	MIN/MAX rise time	1ms/50ms
	MIN/MAX fall time	1ms/5s
	MAX average current	20mA

## Physical Configuration

### U.3/U.2 Enterprise PCIe

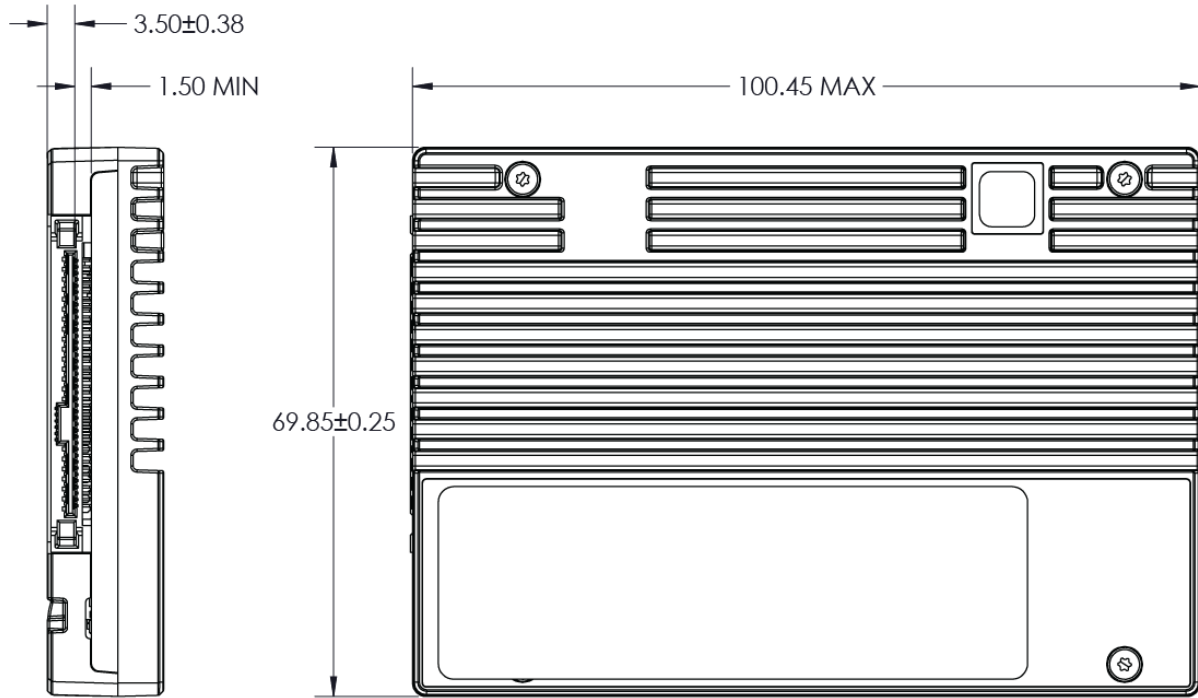
Product mass: less than 235g for U.3 15mm.

Figure 2: U.3/U.2 15mm Nominal Dimensions – 16TB/32TB Capacity Point View



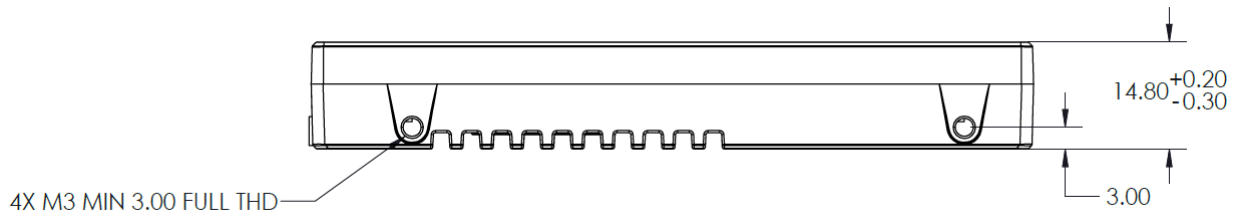
Note: 1. All dimensions are in millimeters.

**Figure 3: U.3/U.2 15mm Nominal Dimensions – 8TB Capacity Point View**



Note: 1. All dimensions are in millimeters.

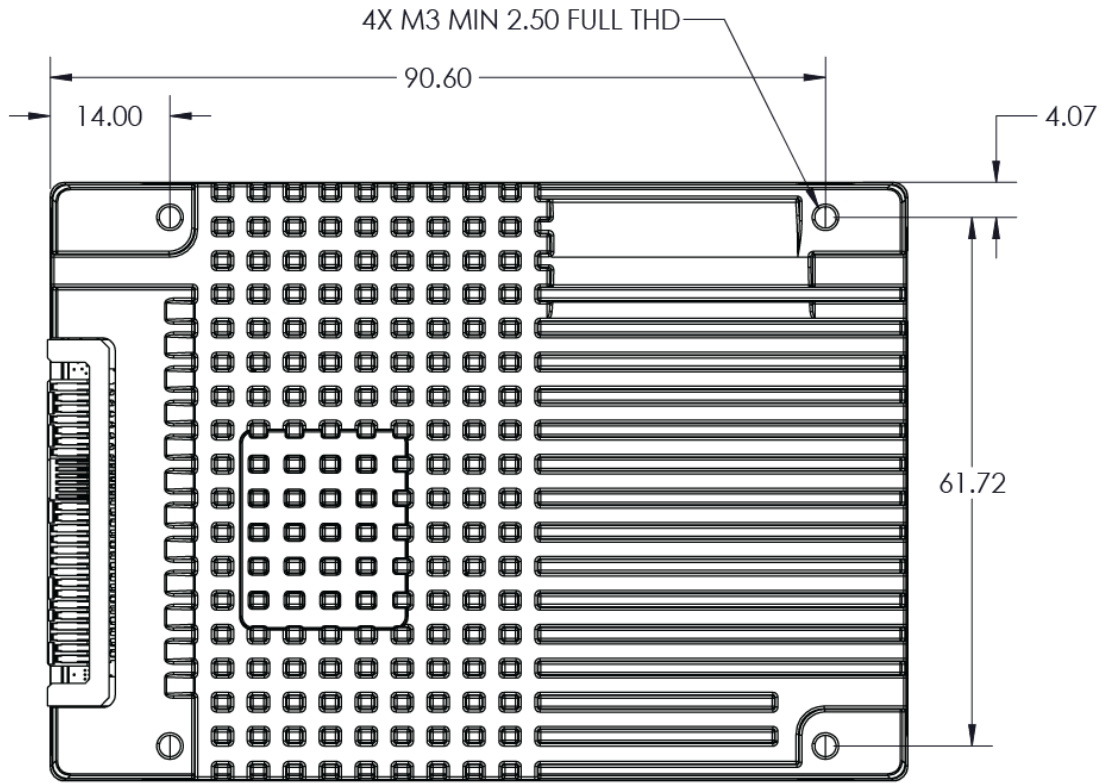
**Figure 4: U.3/U.2 15mm Nominal Dimensions 16TB/32TB – Side View**



Note: 1. All dimensions are in millimeters.



Figure 5: U.3/U.2 15mm Nominal Dimensions 16TB/32TB and 8TB – Bottom View



Note: 1. All dimensions are in millimeters.





## **Revision History**

### **Rev. A – 5/2023**

- Initial release

8000 S. Federal Way, P.O. Box 6, Boise, ID 83707-0006  
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This data sheet contains minimum and maximum limits specified over the power supply and temperature range set forth herein. Although considered final, these specifications are subject to change, as further product development and data characterization sometimes occur.